

ABSTRACT OF THE DISCLOSURE

5 A design support system includes an information
merging section, a connection information generating
section and an inter-semiconductor chip and lead frame
connection information integrating section. The
information merging section captures semiconductor chip
information and lead frame information, and generates
semiconductor chip and lead frame merged information for
each of semiconductor chips. The connection information
10 generating section generates connection information
between the semiconductor chips and lead frame from the
semiconductor chip and lead frame merged information
generated by the information merging section. The
inter-semiconductor chip and lead frame connection
15 information integrating section generates integrated
connection information between the semiconductor chips
and the lead frame, which enables all items of the
connection information between the semiconductor chips
and lead frame to be displayed on one drawing, from the
20 connection information between the semiconductor chips
and lead frame generated by the connection information
generating section. The design support system can solve
a problem of a conventional design support system in that
it is difficult for a user to verify connections between
25 a plurality of semiconductor chips in an MCP (Multi Chip
Package).